

Program Policy

- To develop a strong research interest in your own scientific field.
- To develop multi-disciplinary insight.
- To obtain a capacity for leadership in fields of academia, industry, and government.

Program Period

4 years (beginning from a master's course's 2nd year to the 3rd year of a doctor's course). The program will start in April for all students entering graduate school in April of the current year or October of the previous year.

Qualifications

Students from the Graduate Schools of Science, Engineering, Engineering Science, or Information Science and Technology.

Selection Process and Program Completion

- Students are selected before their doctor's course. Document screening and interviews for acceptance are conducted from February to March.
- A Qualifying Examination (QE) is conducted before students proceed to their doctor's course.
- After passing the PhD defense and the final examination, a certificate of completion for the Honors Program will also be awarded.

(All examinations of this program are conducted according to the rules of each research unit.)



Osaka University Honors Program

for Graduate Schools in Science,
Engineering and Informatics

Since 2020

Honors Program for Graduate Schools in
Science, Engineering and Informatics,
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Broaden your horizons !
OSAKA UNIVERSITY mascot Dr. Wani

About Research Units

All Graduate Schools and Research Institutes and Centers in the science, engineering, and informatics fields at Osaka University jointly organize research units that reach beyond the frames of the graduate schools themselves. Students choose and belong to one of the following research units:

- Electronics and Informatics Research Unit
- Life Science Research Unit
- Photonics Research Unit
- Fundamental and Astro Physics Research Unit
- Environmental Materials & Joining Design Research Unit
- Social Design Research Unit
- Materials Science Research Unit
- Humanware Research Unit
- Pioneering Quantum Beam Application Research Unit

Honors Program Curriculum

Students need to take 10 credits to complete this program.

- Science, Engineering, and Informatics Laboratory Rotation I, II, III, IV (1 to 4 credits)
- Science, Engineering, and Informatics Internship I, II, III, IV (1 to 4 credits)
- English for Science and Engineering (2 credits)
- Ethical, Legal, and Social Issues (2 credits)
- Classes taken in other departments rather than the students' own (2 credits)

*Students will be able to apply part of these credits toward the completion of their master's or doctor's course.



Laboratory Rotation

Students choose another laboratory in their research units and study new research methods and themes for 3 to 9 weeks. This is designed to foster new skills and abilities.



Grant-type Scholarship

After conducting a document review, these scholarships are awarded at 480,000 yen per year to a student starting from the 2nd year of a master's course, and 720,000 yen per year to a student in their doctor's course. These awarded scholarships do not need to be repaid.

♥ Scholarship Qualifications

- In each year, grants are awarded to students in accordance with the conditions below:
- 1) Those who are not taking a leave of absence.
 - 2) Those who do not receive any research fellowships for young scientists from the Japan Society for the Promotion of Science or the Japanese Government Scholarship.
 - 3) Those who do not receive any grant-type scholarships of more than 100,000 yen per month from corporations or foundations.



Internship

Internships (domestic or international) are required. Credits are applied at 1 credit per three-week internship stay. Students are able to decide their destination and internship duties after discussions with their supervisors. A program mentor will provide planning support. This program strongly encourages students to engage in fields and research methods different from their own to broaden their perspective in multiple fields.

■ Internship List

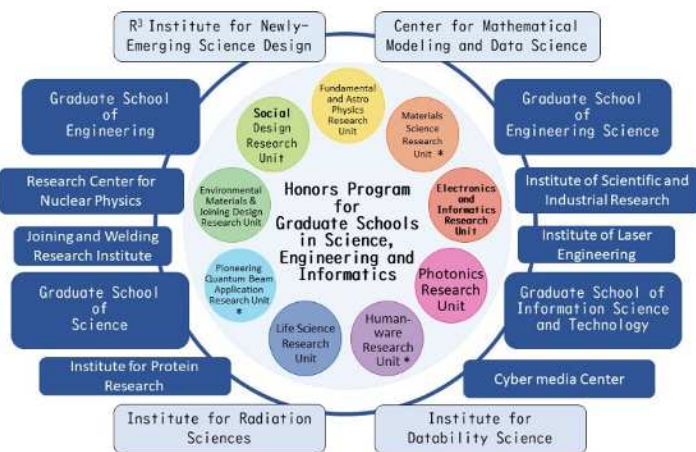
DAIKIN INDUSTRIES, Ltd., Hitachi, Ltd., KANEKA Corporation
 Kawasaki Heavy Industries, Ltd., KYOCERA Corporation
 MAZDA Motor Corporation, Mitsubishi Heavy Industries, Ltd.
 Nitto Denko Corporation, OMRON Corporation
 Panasonic Corporation, Ricoh Company, Ltd.
 Shimadzu Corporation, Sumitomo Chemical Co., Ltd.
 TDK Corporation, Toshiba Corporation

National Institute of Advanced Industrial Science and Technology
 National Institute of Information and Communications Technology
 National Institute for Materials Science
 Institute for Molecular Science
 Institute of Physical and Chemical Research

Thammasat University, National Taiwan University
 Nanjing University, Dalian University of Technology
 Shanghai Normal University, Lanzhou University
 Chongqing University, Xi'an Jiaotong University
 Indian Institute of Technology, Institut Teknologi Bandung
 Seoul National University, Universiti Teknologi Malaysia
 Universiti Sains Malaysia, Chulalongkorn University

Macquarie University, Monash University
 Institut Mines-Télécom, University of Genoa
 Ecole Centrale de Nantes, Imperial College London
 RWTH Aachen University, Vietnam National University, Hanoi
 Technische Universität Dresden, University of Toronto
 University of California, Davis, Istanbul University
 Sharif University of Technology, Universidade de São Paulo

Domestic and international travel expenses for research/training will be supported by this program separate from any scholarships



* The Materials Science Research Unit and Humanware Research Unit are mainly managed by the Program for Leading Graduate Schools schemes, and the Pioneering Quantum Beam Application Research Unit is managed by the Doctoral Program for World-leading Innovative & Smart Education. The content of these programs and application guidelines are different. Please contact the administrative offices of these programs for details.